ON Semiconductor

FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #20724

Generic Copy

Issue Date: 06-Jan-2015

TITLE: Copper wire conversion for LA6571.

PROPOSED FIRST SHIP DATE: 13-Apr-2015

AFFECTED CHANGE CATEGORY(S): Wire Bonding and Mold resin

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or <Takashi.Harashima@onsemi.com>
<Takeshi2.Hoshino@onsemi.com> <Kazumi.Onda@onsemi.com > <Shinya.Okada@onsemi.com >
(Yoshiyuki.Nunokawa@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office < jun.hasunuma@onsemi.com>

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor Sales Office or <Satoru.Fujinuma@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

LA6571 changes the following contents.

1) Changing Bonding Wire from Gold to Copper.
2) Changing Mold resin from Halogen to Halogen free.

The Product design and electrical specifications will remain identical.
Reliability Qualification and full electrical characterization over temperature has been completed on the designated package qualification vehicles.

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RELIABILITY DATA SUMMARY:

Reliability Test Results:

Test Items	Test Condition	Test Time	Results
Steady State Operating Life	Tj=Tjmax, Vcc=Operating max	1000hrs	Pass
Temperature Humidity Bias *	Ta=85degC,RH=85%, Vcc=Recommended	1000hrs	Pass
Temperature Cycle *	Ta=-65degC(30min) ⇔ Ta=150degC (30min)	100cycles	Pass
Pressure Cooker *	Ta=121degC,RH=100% ,205kPa	100hrs	Pass
High Temperature Storage	Ta=150degC	1000hrs	Pass
Resistance to Soldering heat (Reflow Soldering)	255degC,10s (Peak260degC)	2times	Pass

Notes:
The test items with * mark are put into operation after the reflow soldering (at 255degC for 10seconds)
Temperature Humidity Bias Test: Intermittent power application consists of 1h ON and 3h OFF.
Judgment Criteria :
Judgment Criteria are due to the limits of the electrical characteristics in the detail specification.

ELECTRICAL CHARACTERISTIC SUMMARY:

There is no change in the electrical performance. Datasheet specifications remain unchanged.

CHANGED PART IDENTIFICATION:

Affected products will be identified with date code.

List of Affected General Parts:

LA6571-TLM-E
LA6571-MPB-E